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Abstract	The invention includes a thermal transfer device. The device includes a housing which defines at least part of chamber sealed from the atmosphere, and a working fluid contained within the chamber. The housing can be formed of a composition which includes a polymer base matrix having a thermally conductive filler material dispersed therein. The housing can have a thermal conductivity of at least about 10 W/mK. The device can include a wick comprising woven carbon fibers.
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